

# Mould-release agent EH 13.650

The aqueous mould release agent **EH 13.650** is an auxiliary product used in the processing of **ELPECAST®** casting compounds based on epoxy/polurethane resins. Prior to potting, the surface is pre-treated with the mould-release agent to facilitate removing the compound from the mould after curing, without leaving any residue. **EH 13.650** is free from solvents, silicone and grease.

## Characteristics

Colour/appearance	milky liquid
Density at 20 °C [68 °F], DIN EN ISO 2811-1	0.99 ± 0.02 g/cm <sup>3</sup>

Index EH = electro auxiliary product

## Processing



Please read this technical report and the publications listed below carefully before using the product. These sheets are enclosed with the first shipment of product or sample.

### MSDS

The corresponding material safety data sheet contains detailed information and characteristics on safety precautions, environmental protection, transport, storage, handling and waste disposal.

### TI

[Technical information TI 15/3](#) "Protective measures when using chemicals including lacquers, casting compounds, thinners, cleaning agents"



Stir before use

- Ensure that the substrate is clean.
- Apply the mould-release agent **EH 13.650** evenly by spraying, dipping, casting, brushing or wiping with a lint-free cloth.

Depending on the design, the material and surface of the mould, the mould-release agent **EH 13.650** may have to be applied in multiple layers.

- Cure thin layers for approx. 5 min at room temperature and then wipe the surface with a lint-free cloth.

The curing time depends on the quantity applied.

- Carry out pre-trials to ensure an optimum result.

Potting can be effected immediately after curing. The compound must be cured at room temperature.

## Safety recommendations

- When using chemicals, the common precautions should be carefully noted.

## Auxiliary products recommended

- [Cleaning agent R 13.780](#)

For the cleaning of work place and tools, and for cleaning the substrate prior to applying the mould-release agent

## Packaging

The packing units available are indicated in our offer which we will send you upon request.

## Shelf life and storage conditions



Shelf life: In sealed original containers at least 9 months



Storage conditions: +5 °C to +25 °C [+41 °F to +77 °F]



Protect against frost

For warehousing reasons, isolated cases may occur where the shelf life upon shipment is less than the shelf life indicated in this technical report. However, it is ensured that our products have **at least** two-thirds of their shelf life remaining when they leave our company. Labels on containers show shelf life and storage conditions.

## Disclaimer

All descriptions and images of our goods and products contained in our technical literature, catalogues, flyers, circular letters, advertisements, price lists, websites, data sheets and brochures, and in particular the information given in this literature are non-binding unless expressly stated otherwise in the Agreement. This shall also include the property rights of third parties if applicable.

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Any questions? We would be pleased to offer you advice and assistance in solving your problems. Samples and technical literature are available upon request.

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